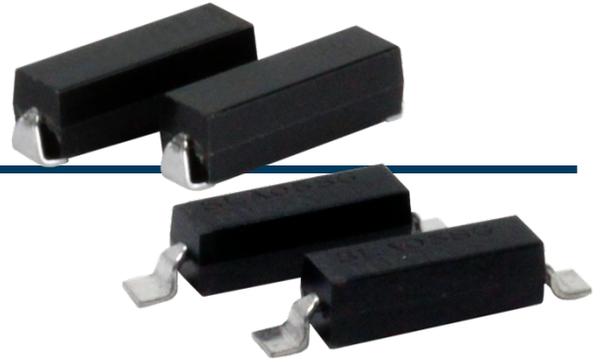




# SLP SERIES

5 to 10kV, 450 to 1000mA, 75nS  
Surface Mount Diodes



## Features

- Long Surface Mount Package
- J Lead or Gullwing Package Option
- Available in Cut Tape and 1000 Piece Reels
- Molded Plastic Body, ANSI/UL94 V-0 Rated Material

## Specifications<sup>1</sup>

Part Number	V <sub>RRM</sub> V	I <sub>FAVM1</sub> <sup>2</sup> mA	I <sub>FAVM2</sub> <sup>2</sup> mA	I <sub>FAVM3</sub> <sup>2</sup> mA	V <sub>F</sub> V	I <sub>R</sub> μA	I <sub>FSM</sub> A	C <sub>J</sub> pF	T <sub>RR</sub> nS	R <sub>θJL</sub> °C/W	R <sub>θJC</sub> °C/W
<b>J Lead Subseries (Figure 1)</b>											
SLP05M	5000	1000	500	500	8.5	0.5	15	7.5	75	17	27
SLP10M	10000	450	230	300	15.8	0.5	15	3.7	75	17	27
<b>Gullwing Subseries (Figure 2)</b>											
SLP05MG	5000	1000	500	500	8.5	0.5	15	7.5	75	17	27
SLP10MG	10000	450	230	300	15.8	0.5	15	3.7	75	17	27

Temperature °C	
Operating Temperature	-55 to 150
Storage Temperature	-55 to 175
Maximum Junction Temperature	150

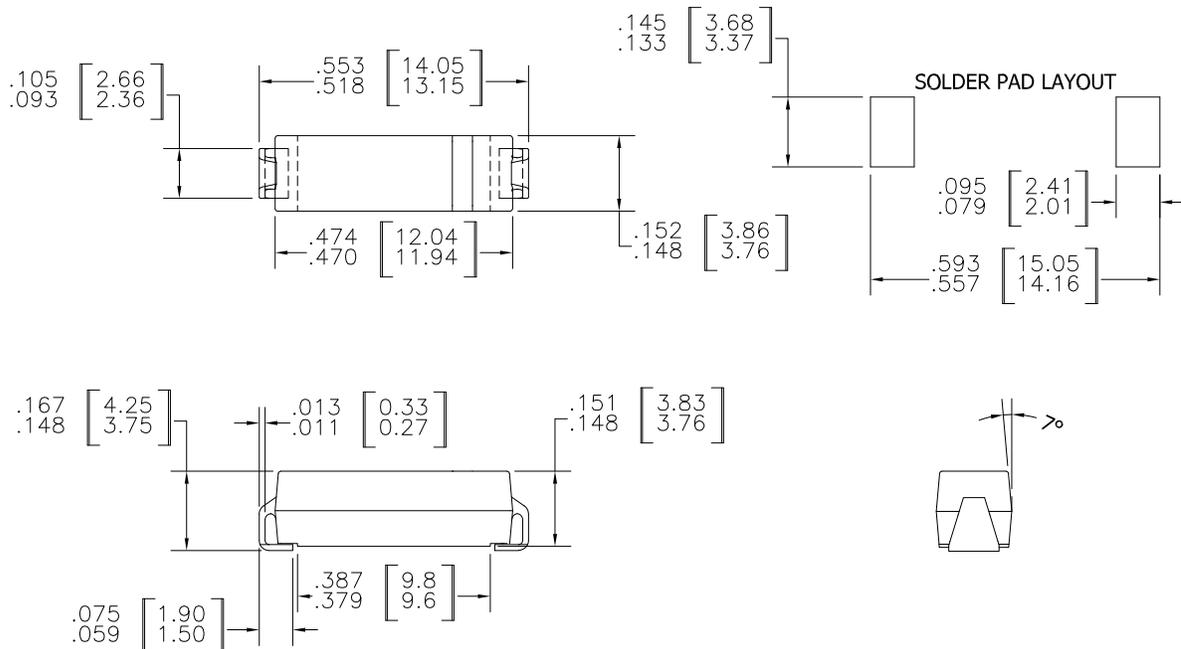
<sup>1</sup>25°C ambient temperature unless stated otherwise.

<sup>2</sup>Check Specification Definitions for conditions details.

## Drawings

Dimensions in inches [mm], tolerances ±0.020 except as noted

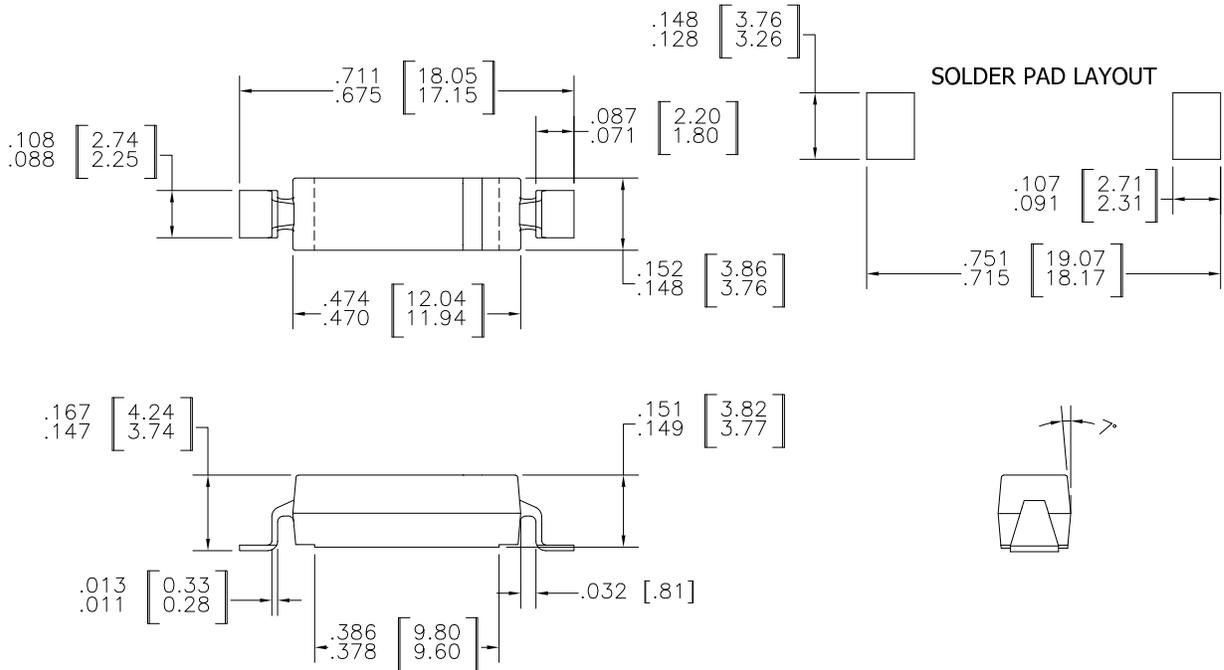
Figure 1 – J Lead Subseries



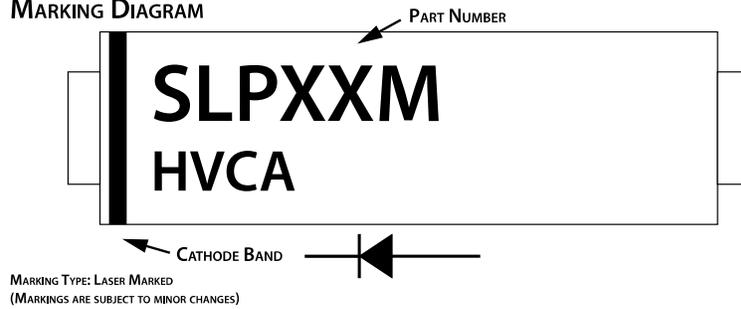


# SLP SERIES

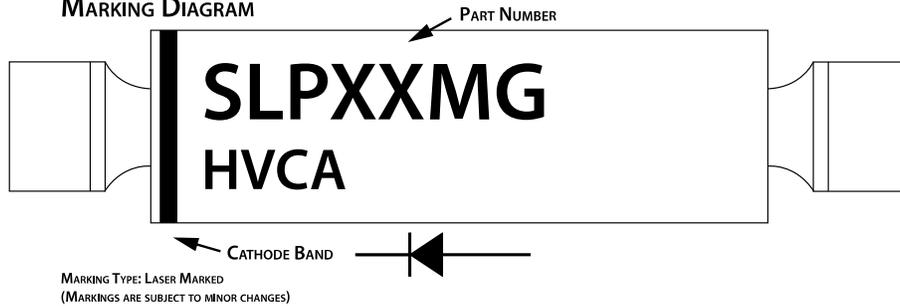
Figure 2 – Gullwing Subseries

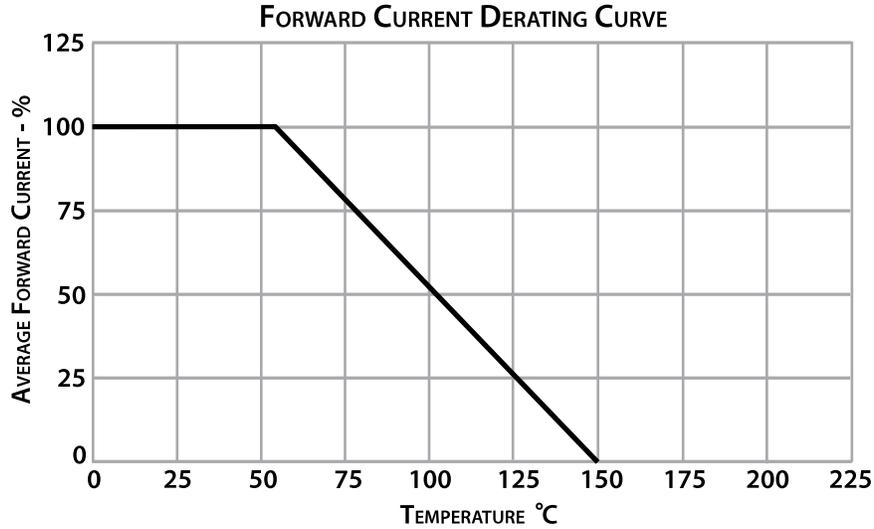


**MARKING DIAGRAM**



**MARKING DIAGRAM**





## Specification Definitions

Specifications		Conditions
<b>V<sub>RRM</sub></b>	Maximum Repetitive Reverse Voltage	-
<b>I<sub>FAVM1</sub></b>	Maximum Average Forward Current	At T <sub>L</sub> = 55°C
<b>I<sub>FAVM2</sub></b>	Maximum Average Forward Current	At T <sub>L</sub> = 100°C
<b>I<sub>FAVM3</sub></b>	Maximum Average Forward Current	At T <sub>C</sub> = 80°C
<b>V<sub>F</sub></b>	Maximum Forward Voltage Drop	At 200mA
<b>I<sub>R</sub></b>	Maximum Leakage Current	At V <sub>RRM</sub>
<b>I<sub>FSM</sub></b>	Maximum Surge Current	At 8.3 mS, Single Half Sine
<b>C<sub>J</sub></b>	Typical Junction Capacitance	At V <sub>R</sub> = 0VDC, f = 1MHz
<b>T<sub>RR</sub></b>	Maximum Reverse Recovery Time	I <sub>F</sub> = 100mA; I <sub>R</sub> = -200mA; I <sub>RR</sub> = -50mA
<b>R<sub>θJL</sub></b>	Typical Thermal Resistance Junction to Lead	Device Mounted on 0.2" x 0.2" (5mm x 5mm) Copper Solder Pads
<b>R<sub>θJC</sub></b>	Typical Thermal Resistance Junction to Case	Device Mounted on 0.2" x 0.2" (5mm x 5mm) Copper Solder Pads

Note: Specifications subject to change without notice. Photo is representation only.

